

REMARKS

Applicants have submitted this Request for Continued Examination so that the Examiner may consider the alternate claims as modified herein. Applicants respectfully request reconsideration of the prior art rejections set forth by the Examiner under 35 USC sections 102 and 103. Applicants respectfully submit that the prior art references of record fail to either teach or suggest the subject matter of the claims as now modified.

More specifically, by this amendment, Applicants have modified the independent claim to additionally require that : the electric device that is housed in the void is directly electrically connected to the conductor pattern via material that is physically in contact with contacts of the electric device and the conductor pattern that is applied to the insulating layer in which the electric device is located. Applicants respectfully submit that neither Nakatani nor Pelligrino teach or suggest these unique and advantageous features of the present invention. In particular, Applicants note that Nakatani merely describes making connections from the chip (electric device) directly with wiring structures located under the chip. In the device of Nakatani, connections with the upper wiring layer that is applied to the insulating layer in which the chip is located are only made by providing a conductive path around the chip. Neither the alternate Pelligrino reference nor any remaining reference of record describes or suggests that the applied wiring layer can be directly connected with the chip that is located within the insulating layer to which the wiring layer is applied. It is only the instant application which describes the unique and advantageous features of the present invention that enables a more compact overall structure

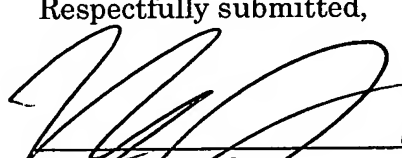
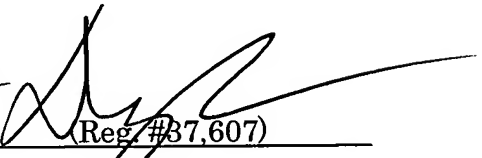
and greater flexibility in design choices for making necessary electrical connections.

The prior art which does not describe this feature has a significant shortcoming and deficiency as a result of the lack of design flexibility which therefore inherently requires a larger and thicker structure. In light of the foregoing, Applicants respectfully submit that all claims now stand in condition for allowance.

In the event that it is deemed necessary, the Commissioner is hereby authorized to charge any fees due or to credit any overpayment to Deposit Account No. 50-3891.

Respectfully submitted,

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Reg. #37,607
Robert J. Depke
ROCKEY, DEPKE, LYONS, LLC
Sears Tower, Suite 5450
Chicago, Illinois 60606-6306
Tel: (312) 277-2006
Attorneys for Applicant